

## IN THE CLAIMS:

Please amend the claims as follows. No new matter is introduced.

1. (Currently Amended) A system of manufacturing a liquid crystal display, the system comprising:

a panel manufacturing unit for manufacturing a liquid crystal panel assembly including a thin film transistor (TFT) array panel, a color filter array panel, and a liquid crystal layer interposed between the TFT array panel and the color filter array panel;

a printed circuit film bonding unit that bonds by compression a printed circuit film on the panel assembly with an adhesive containing a plurality of conductive particles;

a printed circuit board (PCB) bonding unit for bonding a PCB to the printed circuit film; and

an inspection unit for inspecting the bonding of the printed circuit film on the panel assembly and ~~detecting dents generated by the compression, wherein the dents are~~ determining whether a dent number is uniform, wherein the dent number is the number of conductive particles between the gate pads of the TFT array panel and leads on said printed circuit film.

2. (Original) The system of claim 1, wherein the printed circuit film comprises a tape carrier package.

3. (Original) The system of claim 1, wherein the inspection unit comprises a differential camera or a differentials scope.

4. (Original) The system of claim 1, wherein the printed circuit film bonding unit bonds the printed circuit film on the panel assembly with an anisotropic conductive film (ACF).

5. (Original) The system of claim 4, wherein the ACF comprises an adhesive containing a plurality of conductive particles.

6. (Original) The system of claim 5, wherein the printed circuit film bonding unit bonds the printed circuit film on the panel assembly by compression.

7. (Canceled)

8. (Original) The system of claim 1, wherein the inspection unit detects alignment of the printed circuit film with the panel assembly.

9. (Original) The system of claim 1, wherein the bonding inspection unit is incorporated into the printed circuit film bonding unit or the PCB bonding unit.

10. (Canceled)

11. (Currently Amended) The system of claim + 22, wherein one of the sub-units of the bonding inspection unit is incorporated into the printed circuit bonding unit and the other of the sub-units of the bonding inspection unit is incorporated into the PCB bonding unit.

12. (Currently Amended) A method of manufacturing as liquid crystal display, the method comprising:

manufacturing a liquid crystal panel assembly;

bonding a printed circuit film on the panel assembly by thermocompression, wherein the printed circuit film is bonded on the panel assembly with an anisotropic conductive film (ACF) containing a plurality of conductive particles ;

bonding a printed circuit board (PCB) to the printed circuit film, and

inspecting the bonding of the printed circuit film on the panel assembly and detecting dents generated by the compression, wherein the dents are whether a dent

number is uniform, wherein the dent number is the number of conductive particles between the gate pads of the TFT array panel and leads on said printed circuit film.

13-15. (Canceled)

16. (Original) The method of claim 12, wherein the printed circuit film comprises a tape carrier package.

17. (Original) The method of claim 12, wherein the inspection is performed using a differential camera or a differentials scope.

18-21. (Canceled)

22. (Previously Presented) The system of claim 1, wherein the bonding inspection unit comprises two sub-units for inspection before and after the bonding of the PCB, respectively.

23. (Previously Presented) The method of claim 12, wherein the inspection is performed before the bonding of the PCB.

24. (Previously Presented) The method of claim 23, further comprising inspecting the bonding of the printed circuit film on the panel assembly again after the bonding of the PCB.

25. (Previously Presented) The method of claim 12, wherein the inspection is performed after the bonding of the PCB.

26. (Previously Presented) The method of claim 12, further comprising applying the anisotropic conductive film on the panel assembly before bonding a printed circuit film on the panel assembly,

pre-curing the anisotropic conductive film by using a pre-heating head, and pre-pressing the printed circuit film on the anisotropic conductive film.